

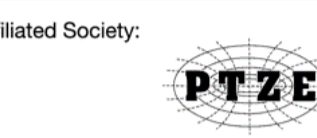
electronics Submit to Electronics Review for Electronics Share

Journal Menu

- Electronics Home Aims & Scope Editorial Board Review Board Topical Advisory Panel Instructions for Authors Special Issues Topics Sections & Collections Article Processing Charge Indexing & Archiving Editor's Choice Articles Most Cited & Viewed Journal Statistics Journal History Journal Awards Society Collaborations Conferences Editorial Office

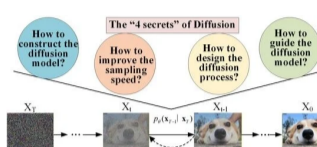
Journal Browser

Volume: issue: Go Forthcoming issue > Current Issue Vol. 15 (2026) Vol. 7 (2018) Vol. 14 (2025) Vol. 6 (2017) Vol. 13 (2024) Vol. 5 (2016) Vol. 12 (2023) Vol. 4 (2015) Vol. 11 (2022) Vol. 3 (2014) Vol. 10 (2021) Vol. 2 (2013) Vol. 9 (2020) Vol. 1 (2012) Vol. 8 (2019)

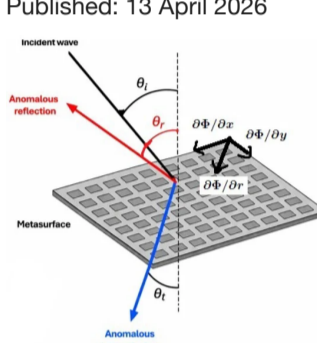


Highly Accessed Articles

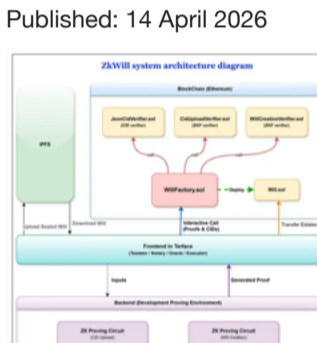
Review Diffusion Models: Unlocking the "4 Secrets" of High-Quality Image Generation by Tao Zhou et al. Electronics 2026, 15(8), 1755; https://doi.org/10.3390/electronics15081755 Published: 21 April 2026



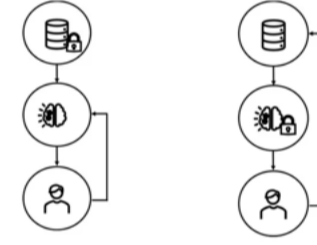
Review Reconfigurable Antennas Enabled by Tunable Metasurfaces for Next-Generation Wireless Communications: A Review by Zahra Hamzavi-Zarghani et al. Electronics 2026, 15(8), 1610; https://doi.org/10.3390/electronics15081610 Published: 13 April 2026



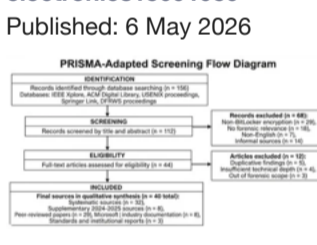
Article Linking Eternity: A Blockchain-Based Framework for Verifiable and Privacy-Preserving Digital Inheritance by Ching-Hsi Tseng et al. Electronics 2026, 15(8), 1642; https://doi.org/10.3390/electronics15081642 Published: 14 April 2026



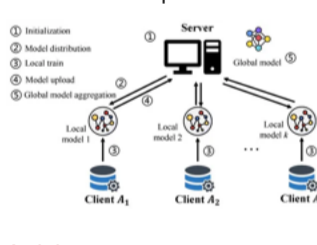
Article Data-Centric AI Manifesto: How Data Quality Drives Modern AI by Donato Malerba et al. Electronics 2026, 15(8), 1913; https://doi.org/10.3390/electronics15081913 Published: 1 May 2026



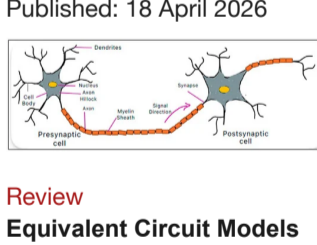
Review The Hardware Isolation Gap: A Systematic Survey of BitLocker Forensics in the TPM 2.0 Era by Vinay Kumar Sankalagere Ramesh et al. Electronics 2026, 15(8), 1959; https://doi.org/10.3390/electronics15081959 Published: 6 May 2026



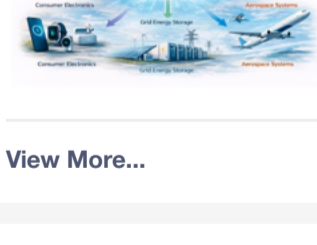
Review Blockchain-Enabled Federated Learning: A Survey on System Design, Key Challenges, and Future Directions by Lingzi Zhu et al. Electronics 2026, 15(8), 1572; https://doi.org/10.3390/electronics15081572 Published: 9 April 2026



Article High-Level Synthesis-Based FPGA Hardware Accelerator for Generalized Hebbian Learning Algorithm for Neuromorphic Computing by Shivani Sharma and Darshika G. Perera Electronics 2026, 15(8), 1725; https://doi.org/10.3390/electronics15081725 Published: 18 April 2026



Review Equivalent Circuit Models for Lithium-Ion Batteries: A Comprehensive Review by Xiao Sun et al. Electronics 2026, 15(8), 1968; https://doi.org/10.3390/electronics15081968 Published: 6 May 2026



View More...

MDPI Books

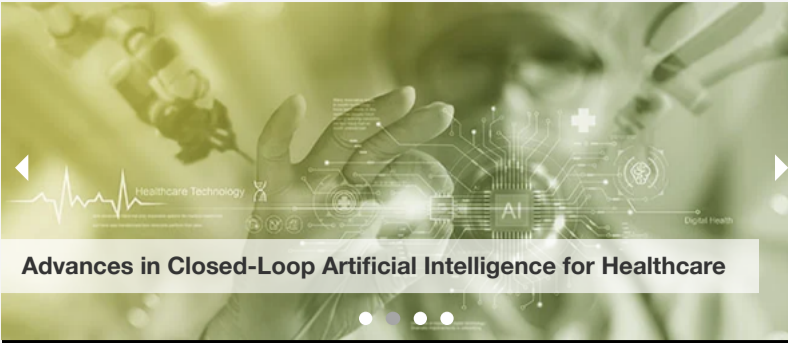
Reprint Intelligent Technologies for Vehicular Networks Editor: Yolanda Blanco Fernández



Reprint Security Challenges and Opportunities of Artificial Intelligence/Big Data Scenarios Editors: Xiaodan Yan, Ke Yan, Muiyi Sun



More Books and Reprints...



Electronics

Electronics is an international, peer-reviewed, open access journal on the science of electronics and its applications published semimonthly online by MDPI. The Polish Society of Applied Electromagnetics (PTZE) is affiliated with Electronics and their members receive a discount on article processing charges.

- Open Access - free for readers, with article processing charges (APC) paid by authors or their institutions. High Visibility: indexed within Scopus, SCIE (Web of Science), CAPPlus / SciFinder, Inspec, Ei Compendex and other databases. Journal Rank: JCR - Q2 (Engineering, Electrical and Electronic) / CiteScore - Q1 (Electrical and Electronic Engineering) Rapid Publication: manuscripts are peer-reviewed and a first decision is provided to authors approximately 16.4 days after submission; acceptance to publication is undertaken in 2.6 days (median values for papers published in this journal in the second half of 2025). Recognition of Reviewers: reviewers who provide timely, thorough peer-review reports receive vouchers entitling them to a discount on the APC of their next publication in any MDPI journal, in appreciation of the work done. Companion journals for Electronics include: Magnetism, Microwave, Network, Signals, Software, Microelectronics, Semiconductors and Heterogeneous Integration and Analog. Journal Cluster of Electronic Engineering and Hardware Systems: Chips, Electronics, Hardware, Journal of Low Power Electronics and Applications, Microelectronics and Microwave.

Impact Factor: 2.6 (2024); 5-Year Impact Factor: 2.6 (2024) Imprint Information Journal Flyer Open Access ISSN: 2079-9292

Latest Articles

Open Access Article Quantifying and Correcting Systemic Offset Errors in PWM and Peak-Valley DC-DC Converters by Devangna Dubey and Gabriel A. Rincón-Mora Electronics 2026, 15(11), 2271; https://doi.org/10.3390/electronics15112271 (registering DOI) - 24 May 2026 Abstract DC-DC converters are ubiquitous in consumer, industrial, commercial, and medical applications. In such voltage-, power-, and area-constrained systems, guaranteeing accurate output voltage remains a key challenge. Investigation of the fundamental cause of steady-state output errors in DC-DC converters, however, is largely absent in [...] Read more. (This article belongs to the Special Issue Section Collection Series: New Horizons and Recent Advances in Power Electronics, 2nd Edition)

Open Access Article Agentic Patterns for Decentralized Network Protocol Configuration by Ahmed Twabi, Yopeng Ding and Tohru Kondo Electronics 2026, 15(11), 2270; https://doi.org/10.3390/electronics15112270 (registering DOI) - 24 May 2026 Abstract Tool-augmented large language model agents are increasingly proposed for network configuration, but routing protocols differ in the control-plane state each commanded router can observe. This difference creates a specific problem for multi-agent orchestration: agents may coordinate more, yet still fail when correct verification [...] Read more.

Open Access Article Enhancing Energy Efficiency and Economic Benefits with Battery Energy Storage Systems: An Agent-Based Optimization Approach by Alfonso González-Briones, Sebastián López Flórez, Carlos Álvarez-López, Carlos Ramos and Sara Rodríguez González Electronics 2026, 15(11), 2269; https://doi.org/10.3390/electronics15112269 (registering DOI) - 24 May 2026 Abstract The emergence of citizen energy communities under the European Clean Energy Package is creating new opportunities for neighboring households to collectively reduce electricity costs through local energy sharing. This paper presents a distributed multi-agent energy management system for a two-household residential energy community [...] Read more. (This article belongs to the Section Artificial Intelligence)

Open Access Article Multi-Scale Gaussian Mixture Model-Gated Mixture of Experts for Fine-Grained Insect Pest Classification by Nurullah Şahin, Nuh Alpaşlan and Davut Hanbay Electronics 2026, 15(11), 2268; https://doi.org/10.3390/electronics15112268 (registering DOI) - 23 May 2026 Abstract Fine-grained insect pest classification presents a particularly demanding visual recognition challenge due to severe class imbalance, pronounced intra-class morphological variability across developmental stages, and high inter-class visual similarity among taxonomically related species. Existing deep learning approaches typically rely on a single feature representation [...] Read more. > Show Figures

Open Access Communication A LoRa-Based IoT Framework for Structural Modal Identification with Levenberg-Marquardt Optimization by Quy Ngoc Vu, Thuy-Binh Nguyen and Toan Thanh Dao Electronics 2026, 15(11), 2267; https://doi.org/10.3390/electronics15112267 (registering DOI) - 23 May 2026 Abstract Structural health monitoring (SHM) is a critical research topic in civil engineering for assessing the integrity of constructed facilities, yet its widespread deployment is often hindered by the high cost of commercial equipment. This study introduces an accessible, vibration-based SHM system consisting of [...] Read more. (This article belongs to the Special Issue Recent Advancements in Sensor Networks and Communication Technologies) > Show Figures

Open Access Article Column-Parallel Adaptive-Gain Single-Slope ADC Using a Single Global Ramp and Column-Local Capacitive Attenuation for High-Speed HDR Imaging by Hyunyoung Yoo, Chanhyuk Park, Minhyun Jin and Myongilae Chu Electronics 2026, 15(11), 2266; https://doi.org/10.3390/electronics15112266 (registering DOI) - 23 May 2026 Abstract This paper presents a column-parallel adaptive-gain single-slope (SS) analog-to-digital converter (ADC) for high-speed high-dynamic-range (HDR) CMOS image sensors. Conventional adaptive-gain approaches often rely on dual-ramp generation or duplicated column circuits, which increase area and power overhead. In contrast, the proposed architecture achieves adaptive-gain [...] Read more. (This article belongs to the Special Issue Low-Voltage Mixed-Signal CMOS Integrated Circuits for Emerging Applications) > Show Figures

Open Access Article Power Optimization Method for Multiple LCC-HVDC Systems Under System Strength Constraints by Jincheng Wu, Ling Xu, Ying Huang, Xiaohu Zhang and Guoteng Wang Electronics 2026, 15(11), 2265; https://doi.org/10.3390/electronics15112265 (registering DOI) - 23 May 2026 Abstract To address the power optimization problem of LCC-HVDC systems in multi-feed receiving-end grids under system strength constraints, this paper systematically analyzes the influence mechanism of AC system strength on conventional DC transmission power, clarifying the quantitative relationship between the critical short circuit ratio [...] Read more. (This article belongs to the Section Industrial Electronics) > Show Figures

Open Access Article A Non-Invasive Voltage Measurement Method for Power Grid Converter Valve Scenarios by Zijian He, Boyuan Gao, Zehao Li, Chuanqi Yang and Pengfei Yang Electronics 2026, 15(11), 2264; https://doi.org/10.3390/electronics15112264 (registering DOI) - 23 May 2026 Abstract Accurate non-invasive voltage measurement is critical for the stable operation of ultra-high-voltage direct-current (UHVDC) grids. In practical converter valve environments, voltage inversion based on the charge simulation method (CSM) may be affected by nearby charged conductors. To address this problem, this paper proposes [...] Read more. > Show Figures

Open Access Article Beyond Sights: A Configurational Analysis of Multisensory Pathways to Electronic Word-of-Mouth in VR Cultural Heritage Systems by Chenyan Jiang, Rui Han, Xiu Hui, Jihong Yu and Shenyu Huang Electronics 2026, 15(11), 2263; https://doi.org/10.3390/electronics15112263 (registering DOI) - 23 May 2026 Abstract Virtual reality heritage experiences can be understood as multisensory interaction systems, yet how auditory, haptic, and gestural cues combine at the system level to shape electronic word-of-mouth (eWOM) remains insufficiently understood. Addressing this problem from a configurational systems perspective, this study applies [...] Read more. (This article belongs to the Special Issue Immersive Realities: Transformations and Challenges in VR, AR, XR, and the Metaverse) > Show Figures

Open Access Article Resilient Event-Triggered Distributed Economic Dispatch Control Strategy Under DoS Attacks by Guangyi Luo, Jintao Yang, Hongke Lang, Weihao Wang, Zhenhao Xu and Jian Le Electronics 2026, 15(11), 2262; https://doi.org/10.3390/electronics15112262 (registering DOI) - 23 May 2026 Abstract Distributed economic dispatch in AC distribution systems relies heavily on communication networks and is therefore vulnerable to denial-of-service (DoS) attacks. To address this issue, this paper proposes a resilient event-triggered distributed economic dispatch control strategy. Two typical DoS attack scenarios, namely communication-link blocking [...] Read more.

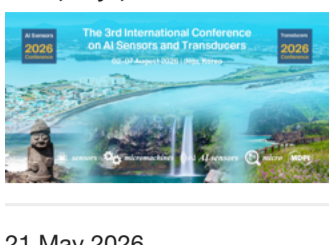
Open Access Article LGP-Net: A Lightweight Gated-Fusion Network with Physics-Informed Features for Automatic Modulation Classification by Xuanchen Liu and Zhuo Chen Electronics 2026, 15(11), 2261; https://doi.org/10.3390/electronics15112261 (registering DOI) - 23 May 2026 Abstract The growing diversity of wireless standards and complex real-world channel effects render automatic modulation classification (AMC) increasingly challenging for spectrum monitoring and edge intelligence. However, most competitive deep-learning-based AMC networks still require 10^6-10^7 parameters, exceeding the memory available on [...] Read more.

More Articles...

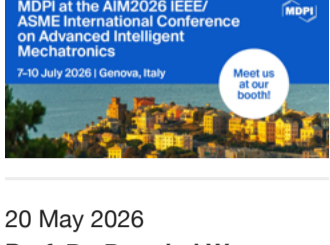
E-Mail Alert Add your e-mail address to receive forthcoming issues of this journal: Enter Your E-Mail Address. Subscribe

News

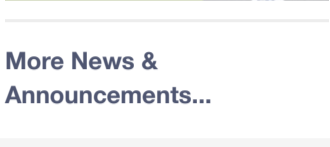
9 October 2025 Meet Us at the 3rd International Conference on AI Sensors and Transducers, 2-7 August 2026, Jeju, South Korea



21 May 2026 Meet Us at the AIM2026 IEEE/ASME International Conference on Advanced Intelligent Mechatronics (AIM2026), 7-10 July 2026, Genova, Italy



20 May 2026 Prof. Dr. Donghai Wu Appointed Section Editor-in-Chief of Section "Semiconductor Devices" in Electronics



More News & Announcements...

Topics

Propose a Topic

Topic in Applied Sciences, Electronics, Micromachines, Sensors, Telecom Microwave Components and Devices: Emerging Technologies and Applications Topic Editors: Sensong An, Bowen Zheng Deadline: 31 May 2026

Topic in AI, Applied Sciences, Education Sciences, Electronics, Information Explainable AI in Education Topic Editors: Guanfeng Liu, Karina Luzia, Luke Bozzetto, Tommy Yuan, Pengpeng Zhao Deadline: 30 June 2026

Topic in Drones, Electronics, Eng, JMSE, Robotics, Sensors, Vehicles Advanced Technologies and Applications for Unmanned Systems Topic Editors: Jinchao Chen, Chao Chen, Yingjie Zhang Deadline: 31 July 2026

Topic in Applied Sciences, Electronics, JSAN, Photonics, Sensors, Telecom Machine Learning in Communication Systems and Networks, 3rd Edition Topic Editors: Yitang Sun, Haeyoung Lee, Oluyomi Simpson Deadline: 20 August 2026

More Topics



Conferences

Propose a Conference Collaboration

1-3 July 2026 Entropy 2026: Exploring Complexity and Information in Science



2-7 August 2026 Abstract Submission Deadline Extended! International Conference on AI Sensors and Transducers Abstract Submission Deadline Extended

7-9 October 2026 International Conference on Intelligent Electronics and Micro/Nanosystems (Intelectro) International Conference on Intelligent Electronics and Micro/Nanosystems 2026

More Conferences...

Special Issues

Propose a Special Issue

Special Issue in Electronics The Future of Cryptography: Trends and Emerging Technologies Guest Editors: Ertem Esiner, Yi-Chun Hu Deadline: 25 May 2026

Special Issue in Electronics Digital Twin Technologies: Industrial Applications and Emerging Research Frontiers Guest Editor: Sanghan Park Deadline: 25 May 2026

Special Issue in Electronics Advanced Energy Management Systems and Power Electronic Solutions for the Next-Generation Smart Grid Guest Editors: Arnel Asongu Nkemb, Nicola Delmonte, Paolo Cova Deadline: 31 May 2026

Special Issue in Electronics Neuromorphic Devices and Brain-Inspired Intelligent Systems: Applications and Prospects Guest Editors: Zhen Cao, Zhang Guo Deadline: 31 May 2026

More Special Issues

Topical Collections

Topical Collection in Electronics Deep Learning for Computer Vision: Algorithms, Theory and Application Collection Editors: Jungong Han, Guiguang Ding

Topical Collection in Electronics Electronics for Agriculture Collection Editors: Lei Shu, Simon Pearson, Ye Liu, Mohamed Amine Ferrag, Leandros Maglaras

Topical Collection in Electronics Computer Vision and Pattern Recognition Techniques Collection Editor: Donghyeon Cho

Topical Collection in Electronics Transition to Industry 4.0 in Emerging Domains: Methodology and Case Studies Collection Editors: Anastasia Rozhok, Roberto Favetria

More Topical Collections

MDPI Further Information Guidelines MDPI Initiatives Follow MDPI Submit to receive issue notifications and newsletters from MDPI journals. Enter your email address. Subscribe. Article Processing Charges Pay an Invoice Open Access Policy Contact MDPI Jobs at MDPI. For Authors For Reviewers For Editors For Librarians For Publishers For Societies For Conferences Organizers. Sciforum MDPI Books Preprints.org Scilit SciProfiles Encyclopedias JAMS Proceedings Series. LinkedIn Facebook X.